

-	50	barrier adj metal adj layer with (argon adj gas or helium adj gas or vacuum or hydrogen adj gas) and copper and temperature and time	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/30 19:19
-	40	barrier adj metal adj layer with (argon adj gas or helium adj gas or vacuum or hydrogen adj gas) and copper and (3\$1 or 4\$1 or 5\$1 or 6\$1 or 7\$1 or 8\$1 or 9\$1 or "100") adj seconds	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/30 19:24
-	39	barrier adj metal adj layer with (argon adj gas or helium adj gas or vacuum or hydrogen adj gas) and copper and temperature and (3\$1 or 4\$1 or 5\$1 or 6\$1 or 7\$1 or 8\$1 or 9\$1 or "100") adj seconds	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/30 19:51
-	621	(438/683).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/30 19:51
-	1133	(438/687).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/30 19:52
-	1191	(438/643).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/30 19:52
-	235	(438/644).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/30 19:52
-	3	barrier adj metal adj layer near (argon adj gas or helium adj gas or vacuum or hydrogen adj gas) and copper and temperature	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/02 16:49
-	3	barrier adj metal near (argon adj gas or helium adj gas or vacuum or hydrogen adj gas) and copper and temperature	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/02 16:49
-	1153	tin with (argon adj gas or helium adj gas or vacuum or hydrogen adj gas) and copper and temperature and seconds	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/02 18:20
-	537	tin with (argon adj gas or helium adj gas or vacuum or hydrogen adj gas) and copper and temperature and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/02 18:21
-	14	tin near (argon adj gas or helium adj gas or vacuum or hydrogen adj gas) and copper and temperature and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/02 18:21
3	1449	(438/680).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/02 19:25
2	623	(438/660).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/02 19:25

1	2133	(438/586).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/02 19:08
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L Number	Hits	Search Text	DB	Time stamp
-	726	barrier adj metal adj layer and (helium or vacuum or hydrogen) and copper	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/02 19:07
-	84	barrier adj metal adj layer with (helium or vacuum or hydrogen) and copper	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/04/30 15:48
-	93	barrier adj metal adj layer with (argon or helium or vacuum or hydrogen) and copper	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/04/30 15:49
-	56	barrier adj metal adj layer with (argon adj gas or helium adj gas or vacuum or hydrogen adj gas) and copper	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/04/30 16:50
-	81	barrier adj metal adj layer same (argon adj gas or helium adj gas or vacuum or hydrogen adj gas) and copper and temperature	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/04/30 16:49
-	54	barrier adj metal adj layer with (argon adj gas or helium adj gas or vacuum or hydrogen adj gas) and copper and temperature	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/02 16:46
-	50	barrier adj metal adj layer with (argon adj gas or helium adj gas or vacuum or hydrogen adj gas) and copper and temperature and seconds	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/02 18:19
-	3	wei-pan.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/04/30 17:10
-	55	pan-wei.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/04/30 17:10
-	23	pan-wei.in. and barrier adj metal and copper	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/04/30 18:12
-	2	Maa-jer-shen.in. and barrier adj metal and copper	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/04/30 18:13
-	0	evans-david-r..in. and barrier adj metal and copper	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/04/30 18:13
-	17	evans-david-r.in. and barrier adj metal and copper	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/04/30 18:14